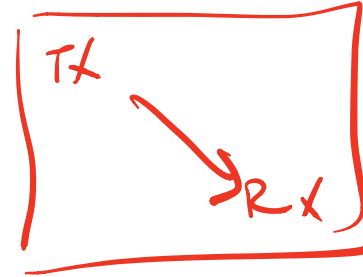


A Bit of Analysis on Self-Timed Single-Bit On-Chip Links

Jonathan Tse, Benjamin Hill, and Rajit Manohar
Computer Systems Laboratory, Cornell University

May 21, 2013

Single-Bit Interconnect



- ▶ Transmit data across die(s)
- ▶ How best to do that?
- ▶ Scope
 - ▶ Single-bit links
 - ▶ Asynchronous context
 - ▶ Delay-Insensitive Encodings
 - ▶ Handshaked links



Interconnect Design Challenges

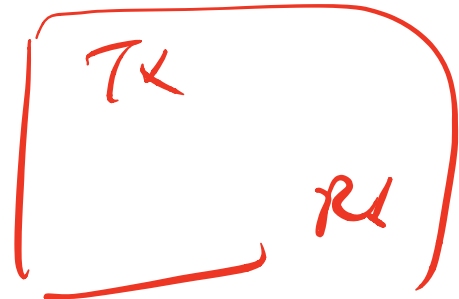
- ▶ Pressure on Wiring Resources
 - ▶ Planar wiring (mostly) plentiful
 - ▶ Interconnect heavy-designs (FPGAs, etc)
 - ▶ Thru-Silicon Vias (TSVs) comparatively scarce
 - ▶ Delay-insensitive encodings expensive
- ▶ Electrical Characteristics
 - ▶ RC characteristics not scaling well
 - ▶ Lumped capacitance model invalid
 - ▶ Long wires — charge relaxation problem

Efficient Wire Usage

- ▶ Synchronous Most Wire-Count Efficient
 - ▶ Bundled data, etc. are close
 - ▶ Delay insensitive encodings worse
- ▶ Asynchronous Protocols Contextually Appropriate
 - ▶ 2-phase computation difficult
 - ▶ 4-phase dual-rail long distance signaling expensive

Choosing a Protocol

- ▶ What does “optimal” mean?
 - ▶ Area
 - ▶ Energy
 - ▶ Throughput
 - ▶ Latency
 - ▶ Ease of design
 - ▶ Robustness
- ▶ Approaching Optimality
 - ▶ Sizing
 - ▶ Circuit family
 - ▶ Buffer insertions
 - ▶ Metallization choices

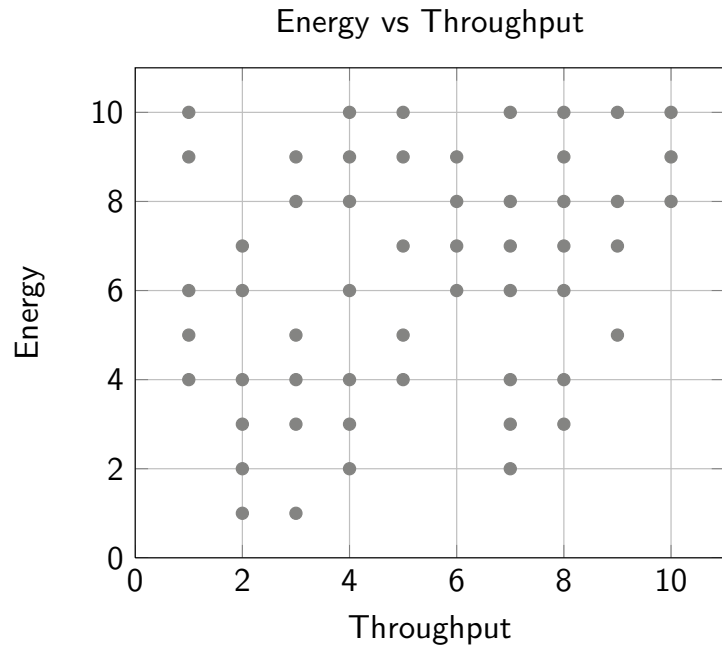


Pareto Front

- ▶ Three Metrics
 - ▶ Throughput
 - ▶ Energy
 - ▶ Area
- ▶ Best Tradeoff

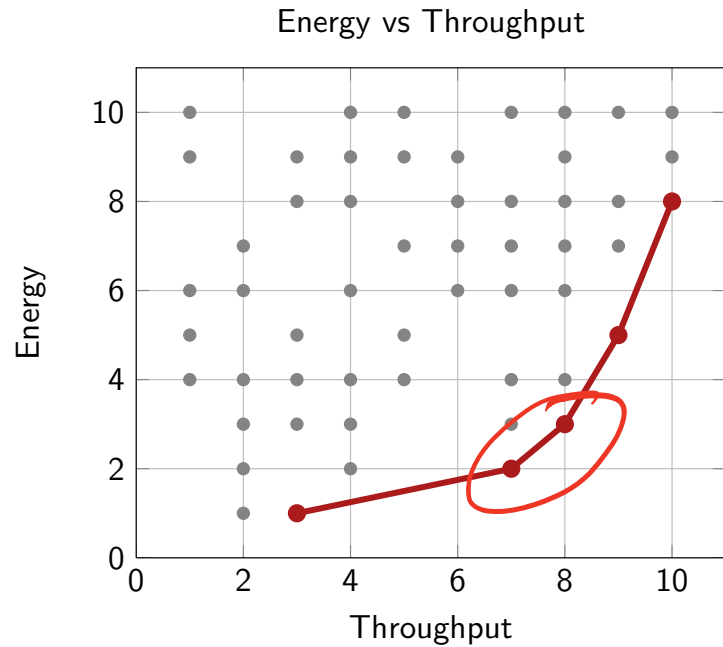
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Pareto Front

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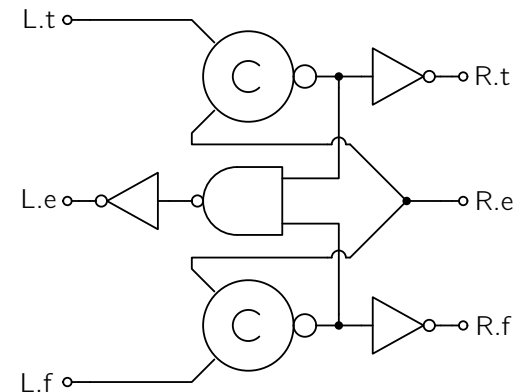
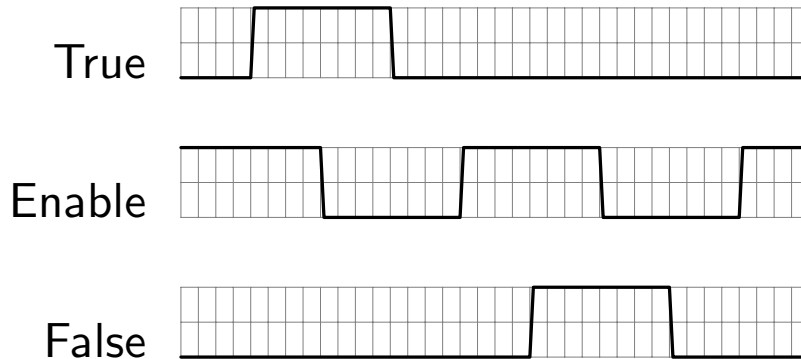


Single-Bit Links

Link	Handshake	Timing	Voltage	Wires
WCHB	4-Phase	QDI	Full-Swing	3
RQDI	2-Phase NRTN	RQDI	Full-Swing	3
STFB	2-Phase RTN	Single-Track	Full-Swing	2
ATLS	4-Phase	QDI	Ternary	2
STATS	2-Phase RTN	Single-Track	Ternary	1

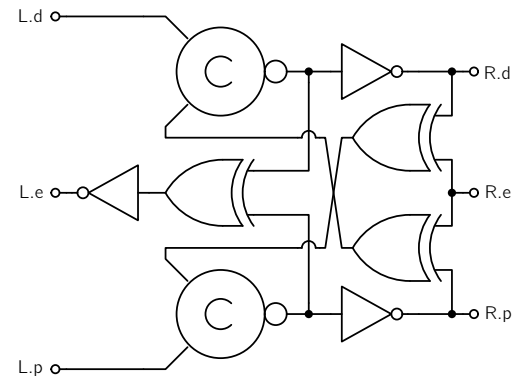
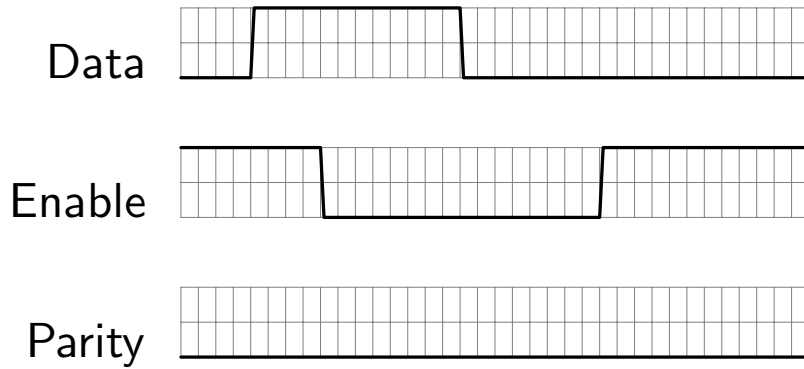
Single-Bit Links

	Link	Handshake	Timing	Voltage	Wires
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	RQDI	2-Phase NRTN	RQDI	Full-Swing	3
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	STATS	2-Phase RTN	Single-Track	Ternary	1



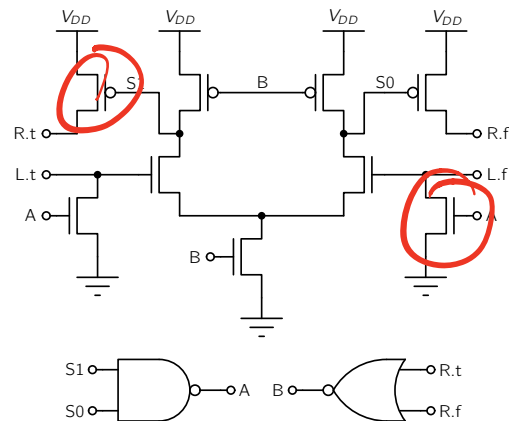
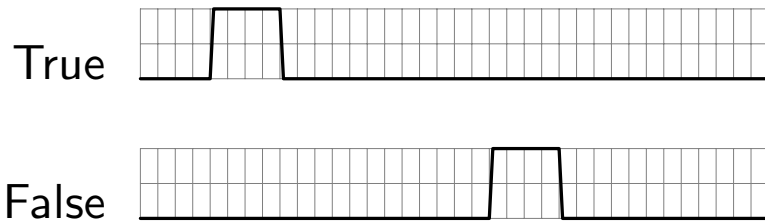
Single-Bit Links

Link	Handshake	Timing	Voltage	Wires
WCHB	4-Phase	QDI	Full-Swing	3
→ RQDI	2-Phase NRTN	RQDI	Full-Swing	3
STFB	2-Phase RTN	Single-Track	Full-Swing	2
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STATS	2-Phase RTN	Single-Track	Ternary	1



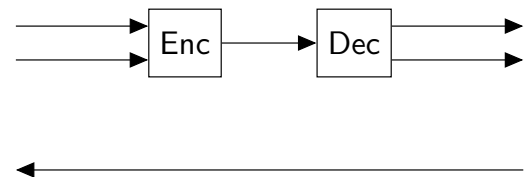
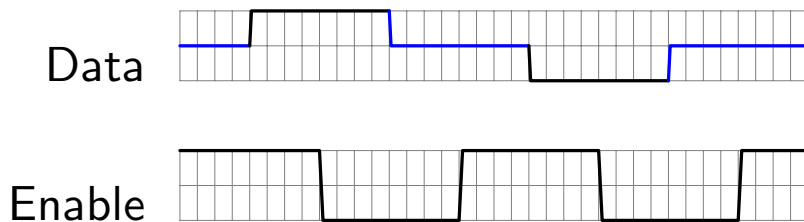
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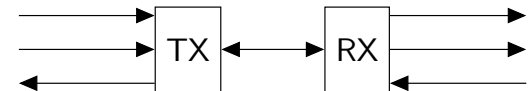
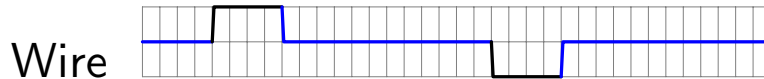
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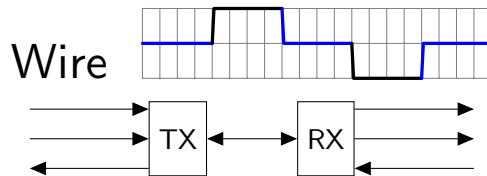


Single-Bit Links

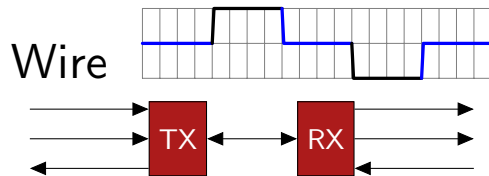
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Single Track Asynchronous Ternary Signaling (STATS)

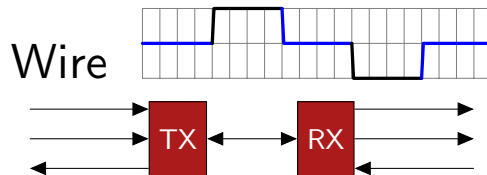


Single Track Asynchronous Ternary Signaling (STATS)

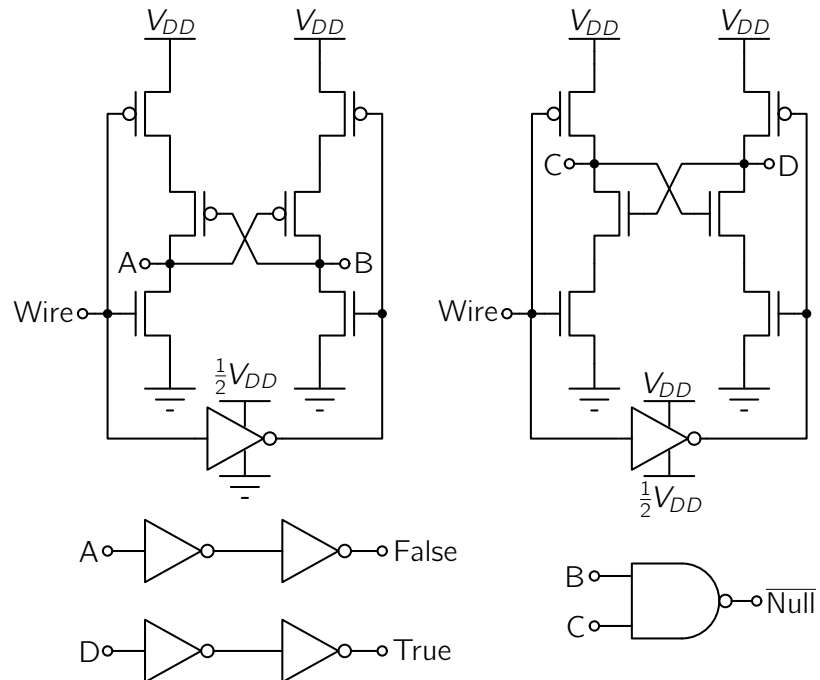


► $\frac{1}{2} V_{DD}$ Supply

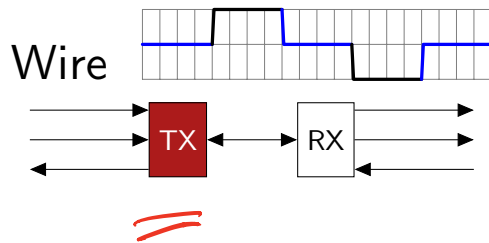
Single Track Asynchronous Ternary Signaling (STATS)



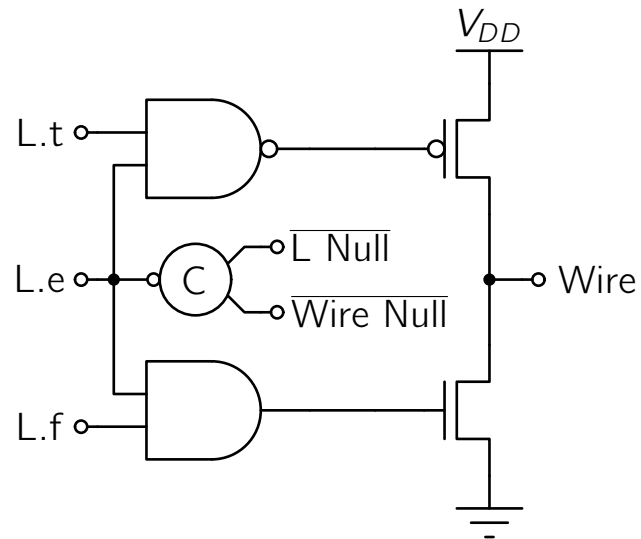
- ▶ $\frac{1}{2} V_{DD}$ Supply
- ▶ Ternary Decode



Single Track Asynchronous Ternary Signaling (STATS)



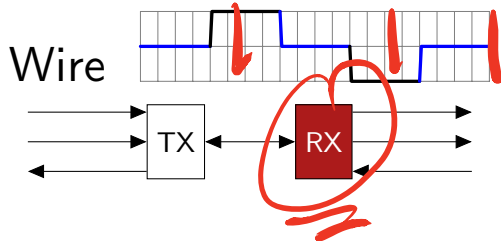
- ▶ $\frac{1}{2} V_{DD}$ Supply
- ▶ Ternary Decode
- ▶ Sending Tokens



Single Track Asynchronous Ternary Signaling (STATS)

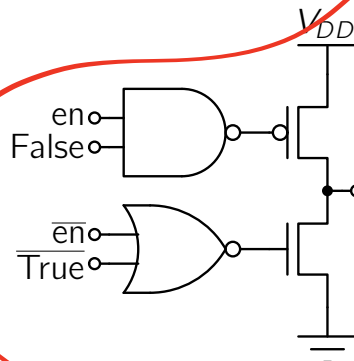
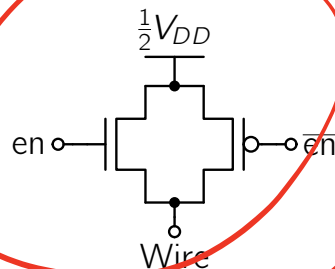
A B C → transfer signals

0 0 0
0 1 0

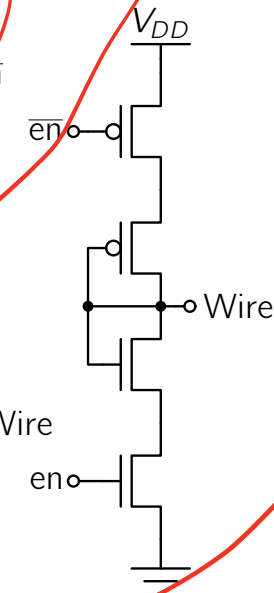


- ▶ $\frac{1}{2} V_{DD}$ Supply
- ▶ Ternary Decode
- ▶ Sending Tokens
- ▶ Return to Null

a) Passgate



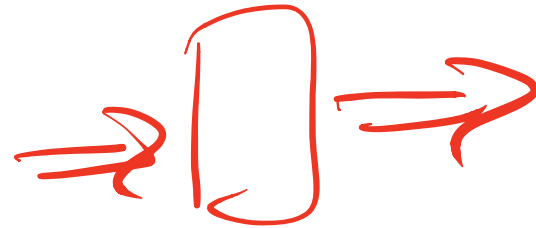
b) Self-Invalidating Driver



c) Shorted Inverter

Heuristic Optimization

- ▶ Global Optimum?
 - ▶ Sizing problem is convex
 - ▶ Other non-sizing factors to consider
- ▶ Heuristic Optimization Techniques
 - ▶ General-purpose
 - ▶ Non-convex problems
 - ▶ Handles local optima
 - ▶ Flexible
 - ▶ Easy implementation



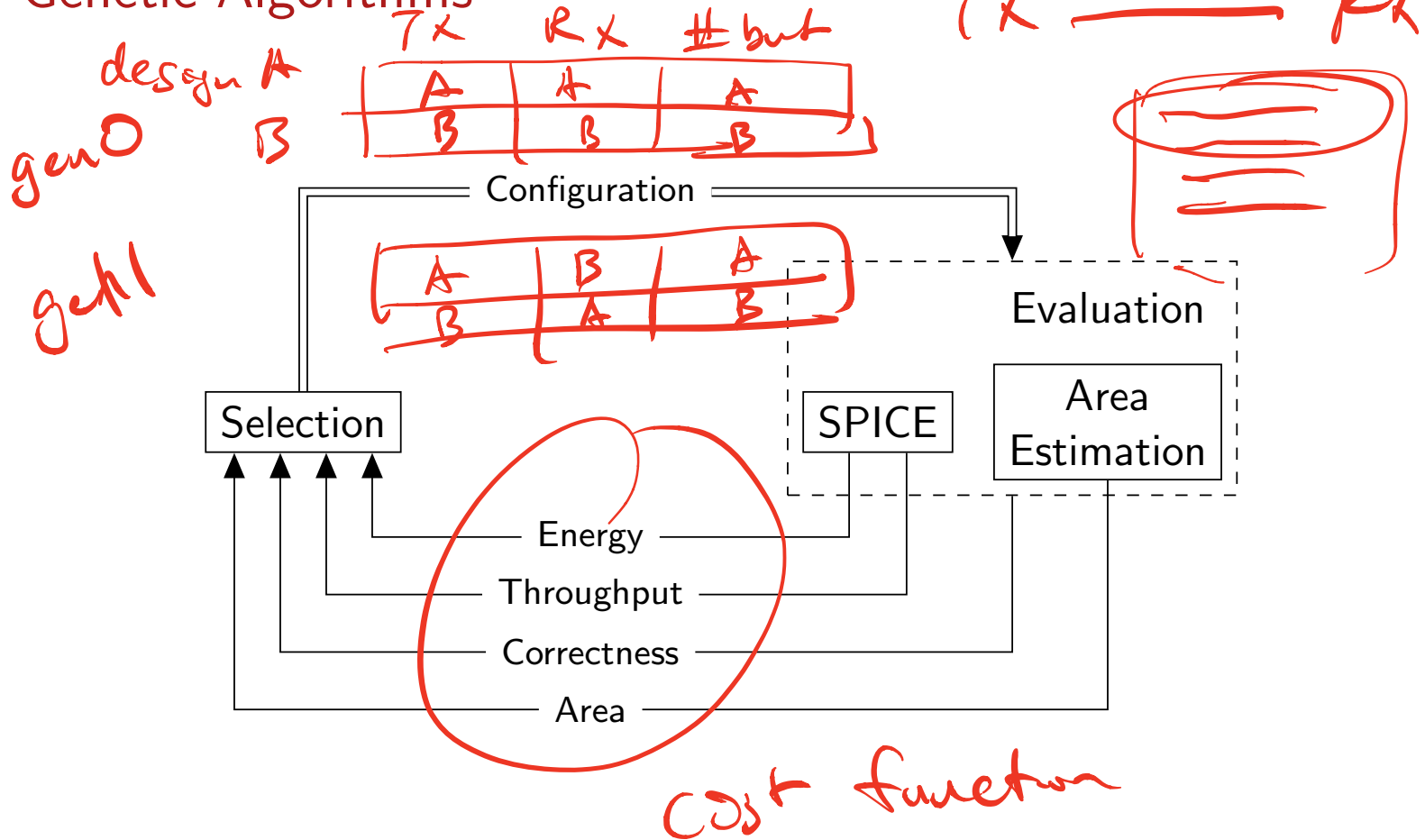
↑
size this

$T - D_0 - D_2 - \dots$

$+ (D_0 - D_2)$

Some number
of this

Genetic Algorithms

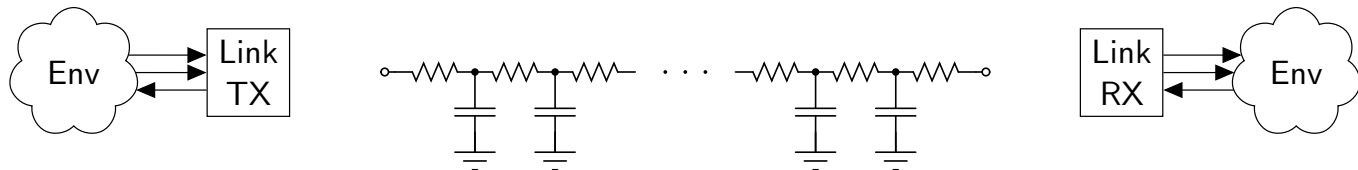


Evaluation

- ▶ Planar Wiring and TSV Cases
- ▶ 4-phase Dual-Rail Environment
- ▶ Configurations
 - ▶ Sizing
 - ▶ Circuit Topology
 - ▶ V_{DD} Scaling (Non-Ternary)
- ▶ Metrics
 - ▶ Throughput
 - ▶ Energy
 - ▶ Area

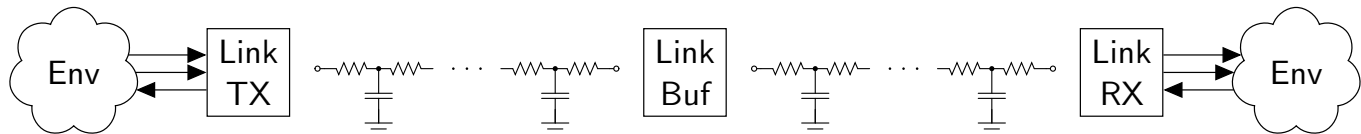
Planar Evaluation

- ▶ Distributed RC Wiring Model
- ▶ Dual-Rail Source/Sink
- ▶ Insert Buffers

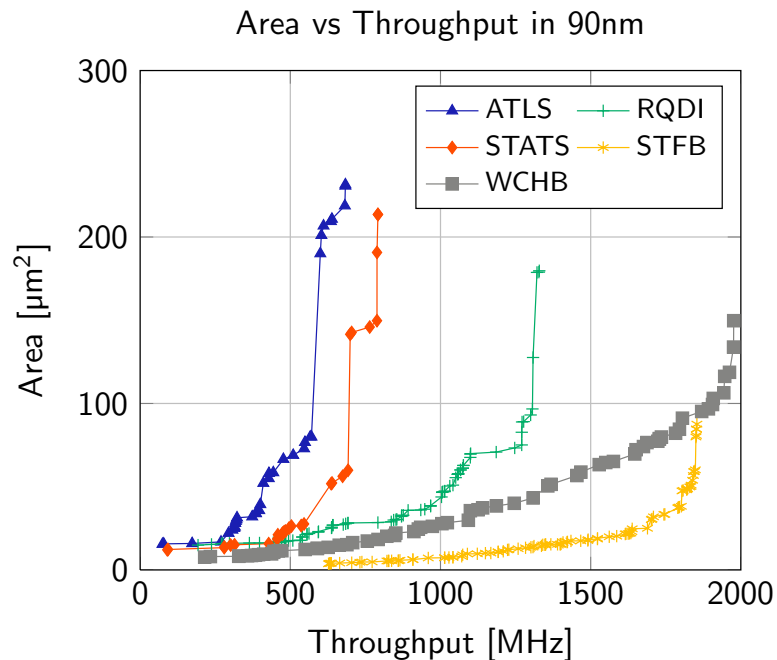
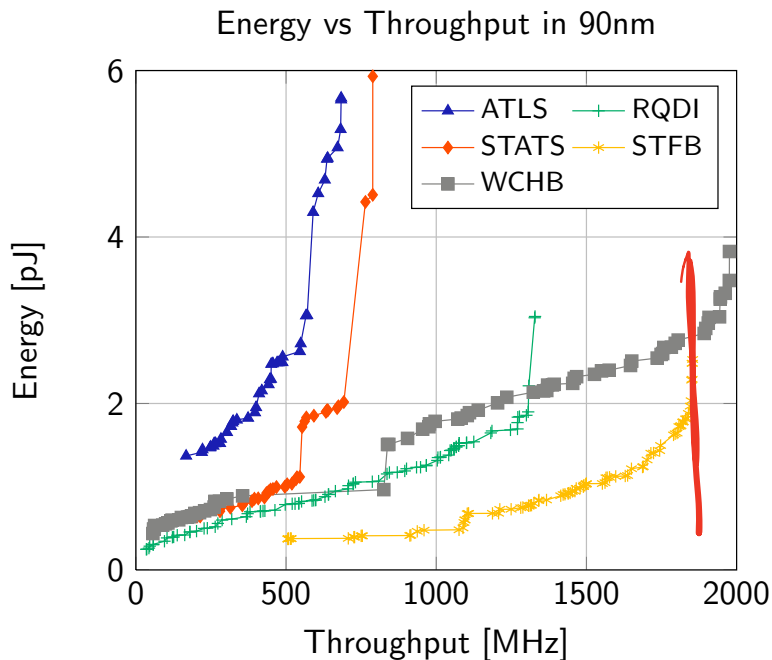


Planar Evaluation

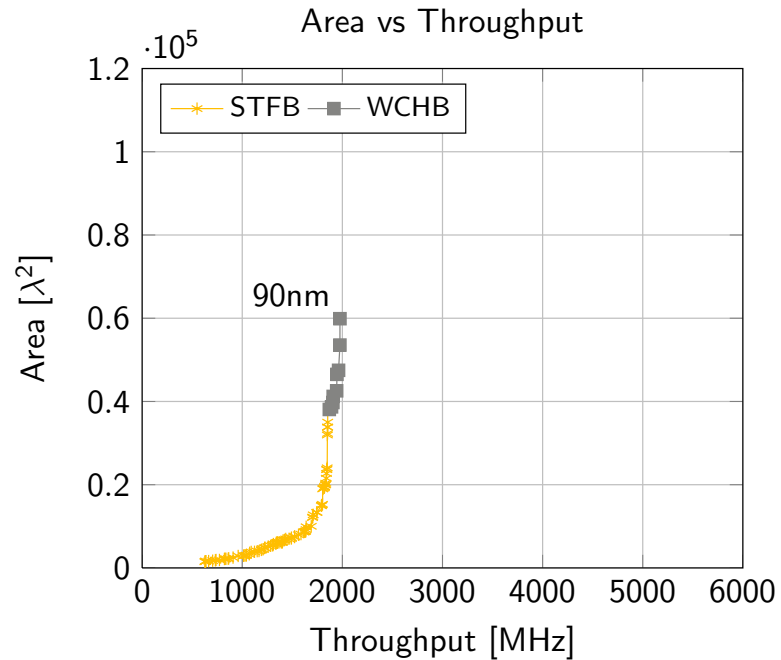
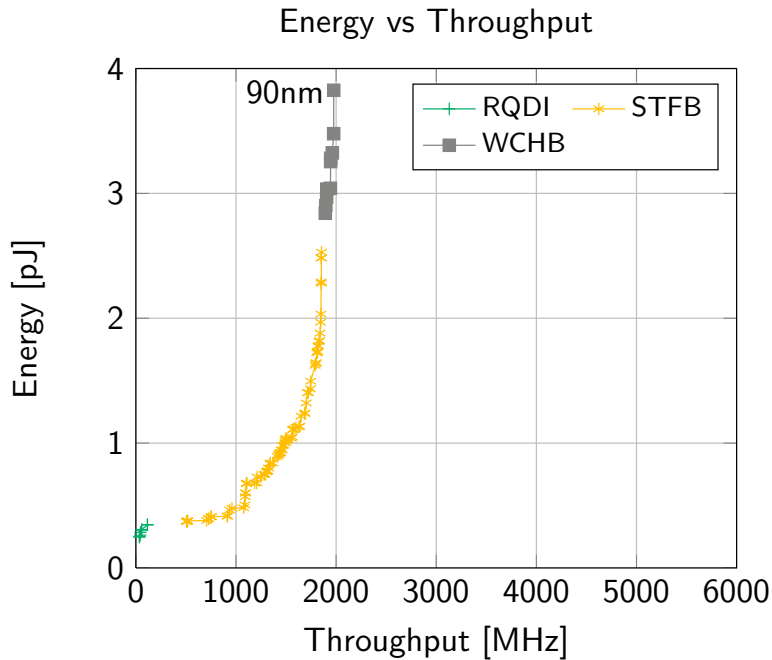
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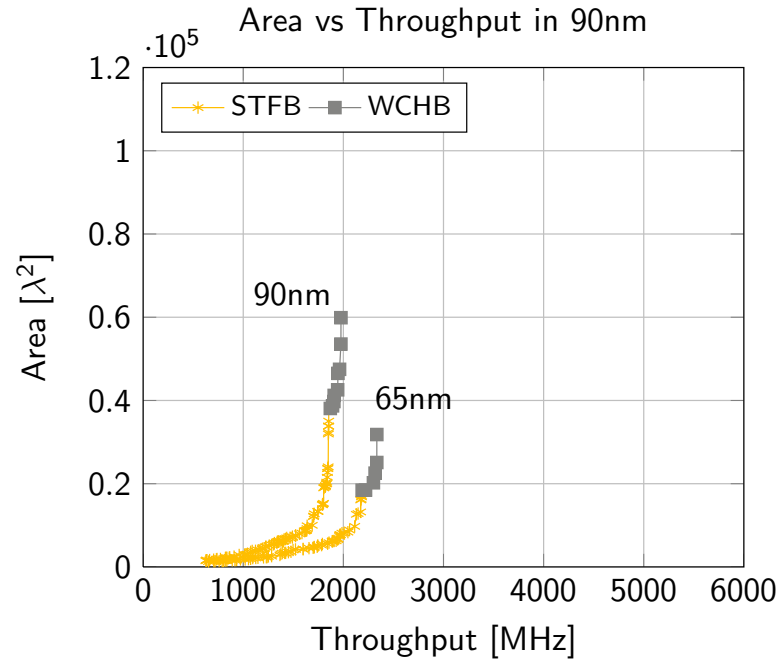
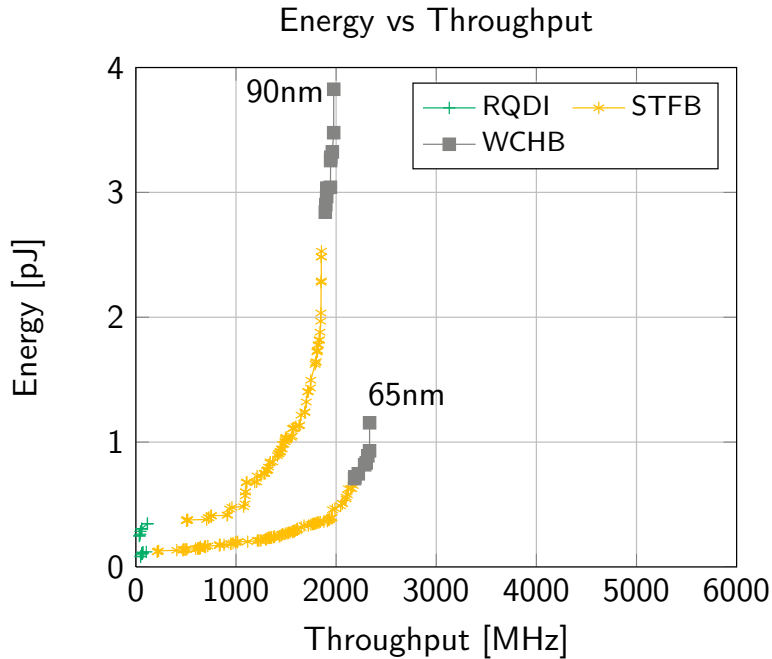
Planar Results in 90nm



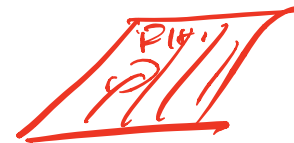
Cross-Technology Planar Results



Cross-Technology Planar Results

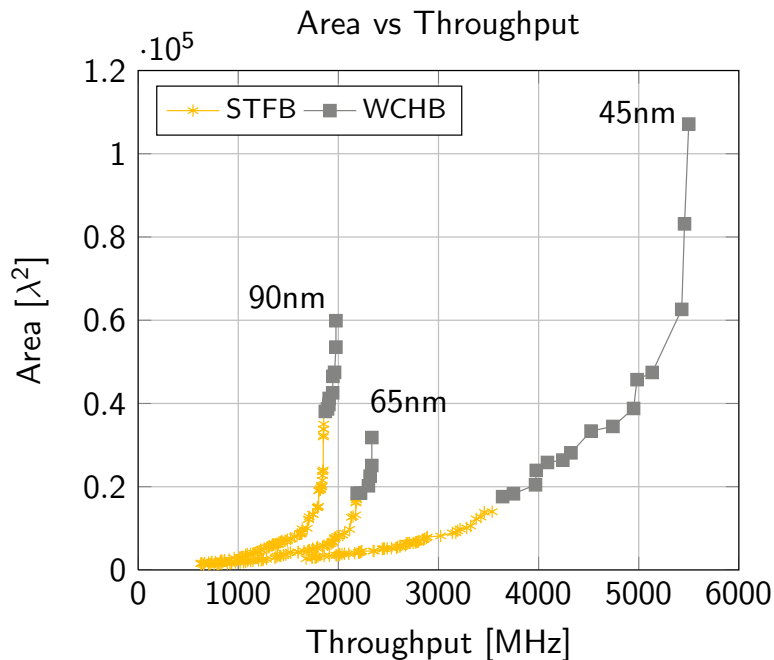
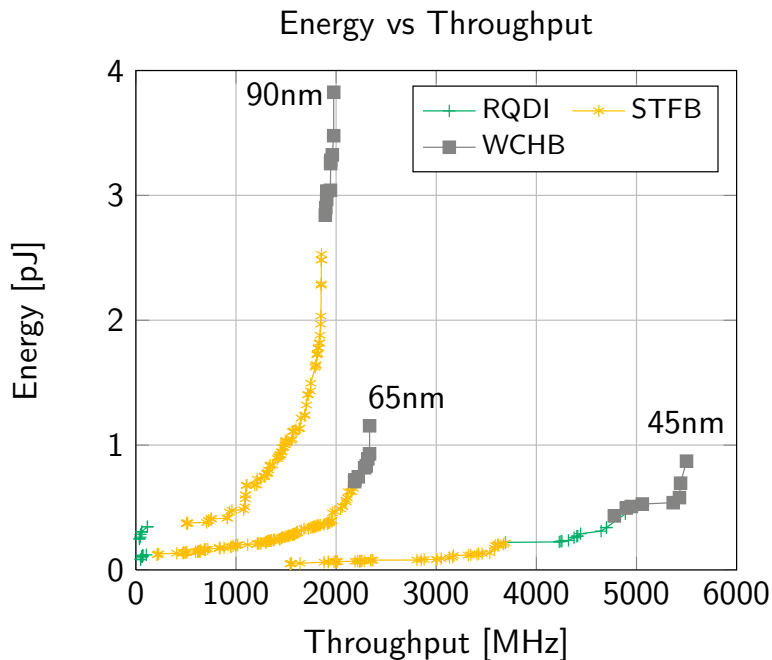


$a \times b$



7111
X0010

Cross-Technology Planar Results

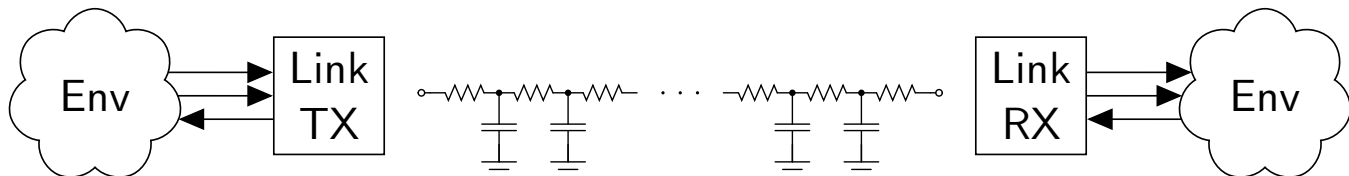


Planar Takeaway Points

- ▶ Single-Track Timing Assumption
 - ▶ STFB offers benefits in Energy, Area
 - ▶ WCHB, RQDI more conservative
- ▶ Ternary buffers are expensive
 - ▶ Perform poorly in high-resistance environments
 - ▶ Ternary conversion cost high

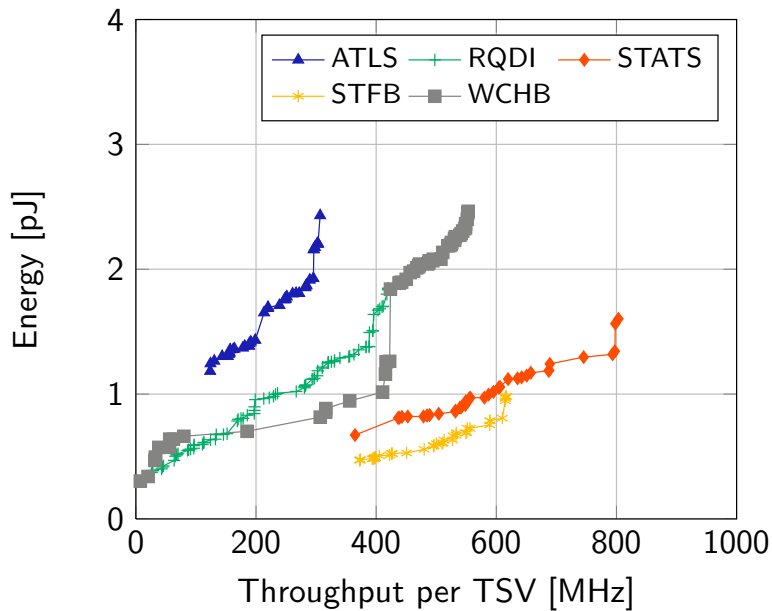
TSV Evaluation

- ▶ Pair of Buffers
- ▶ No Intermediary Buffers
- ▶ TSVs
 - ▶ Doesn't scale with technology
 - ▶ Less dense than planar
 - ▶ Wire-efficiency important
 - ▶ Scale throughput by TSV usage

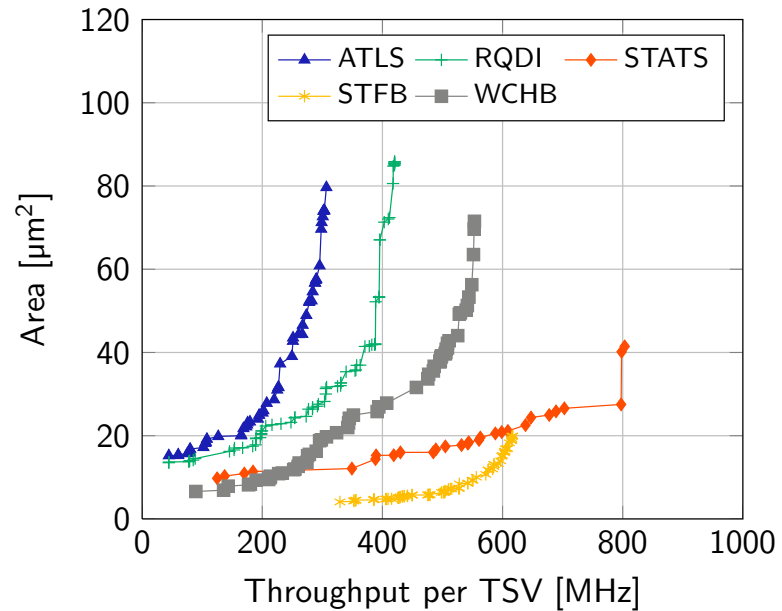


TSV Results in 90nm

Energy vs Scaled Throughput in 90nm

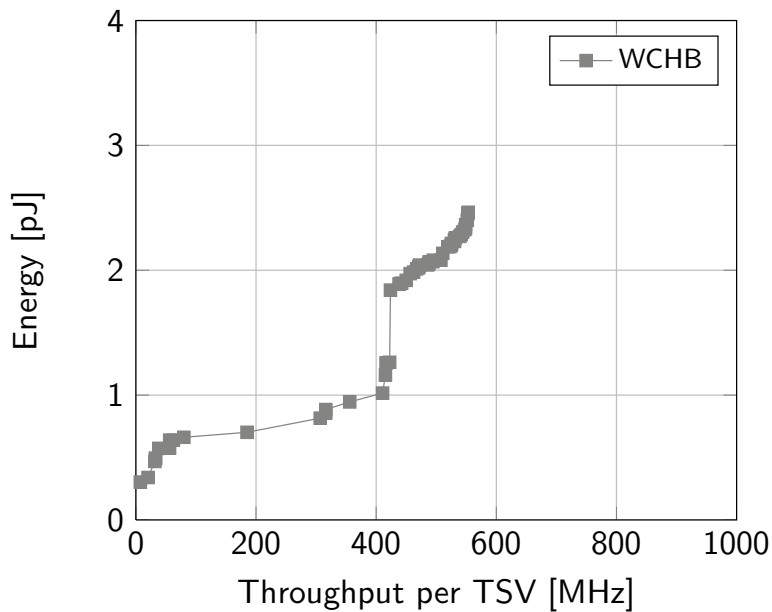


Area vs Scaled Throughput in 90nm

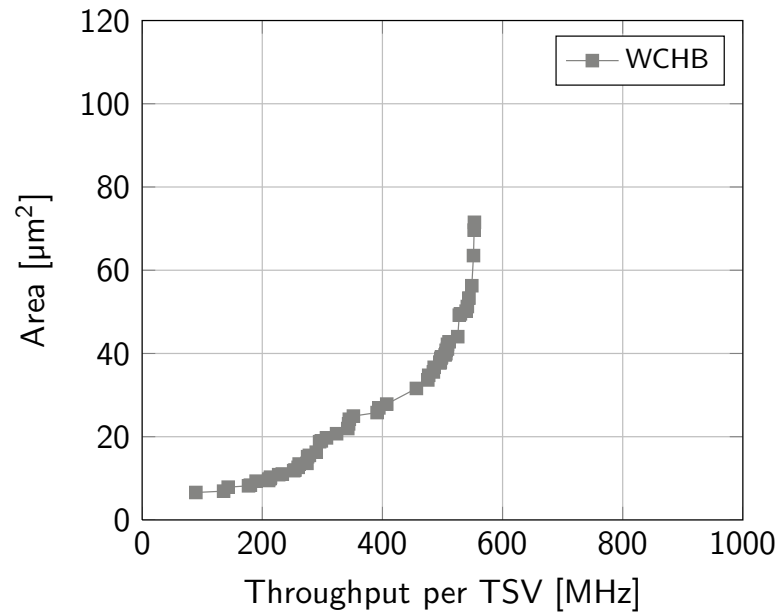


TSV Results in 90nm

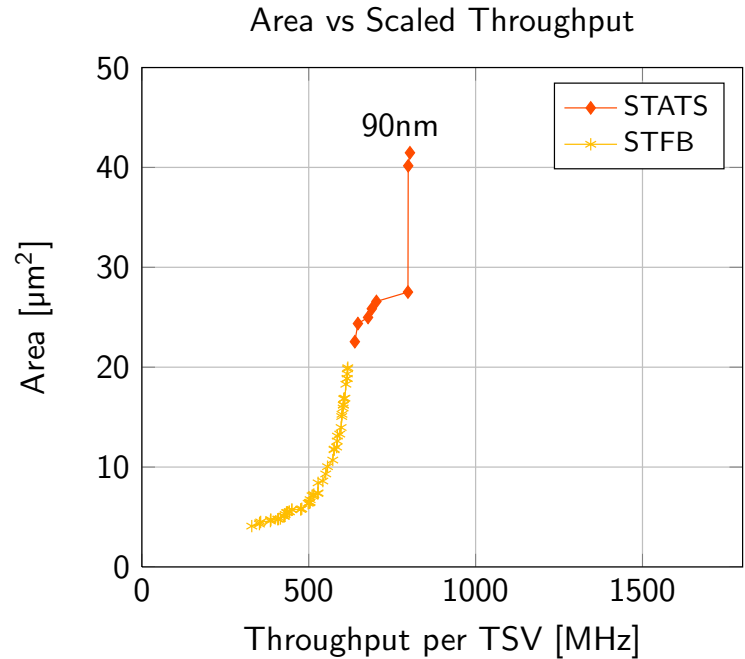
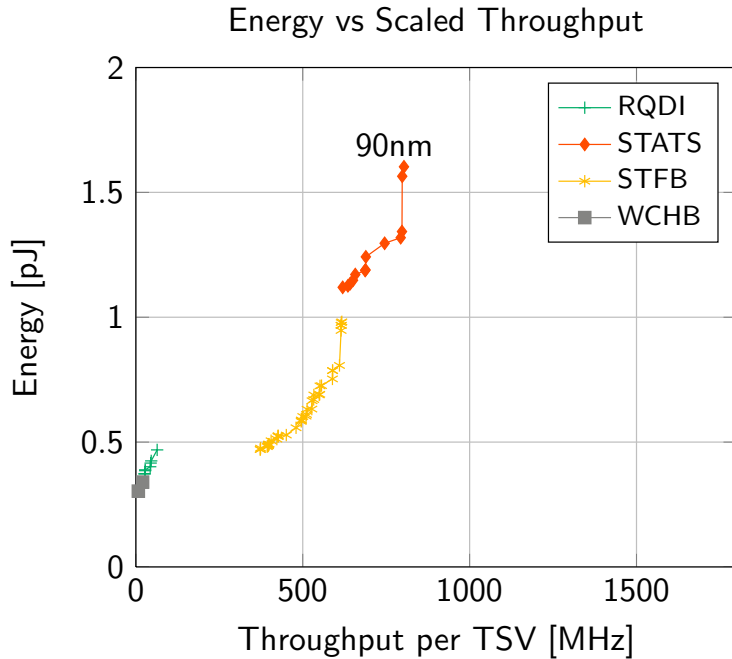
Energy vs Scaled Throughput in 90nm



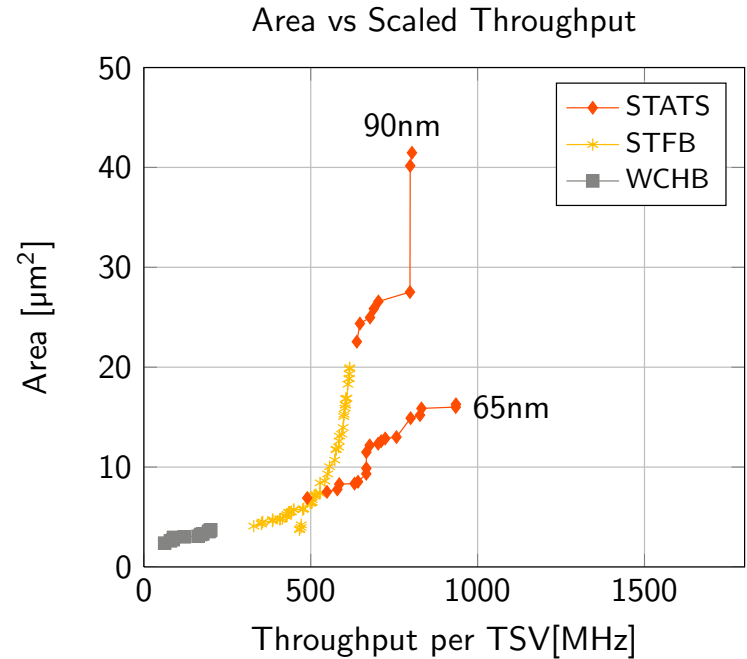
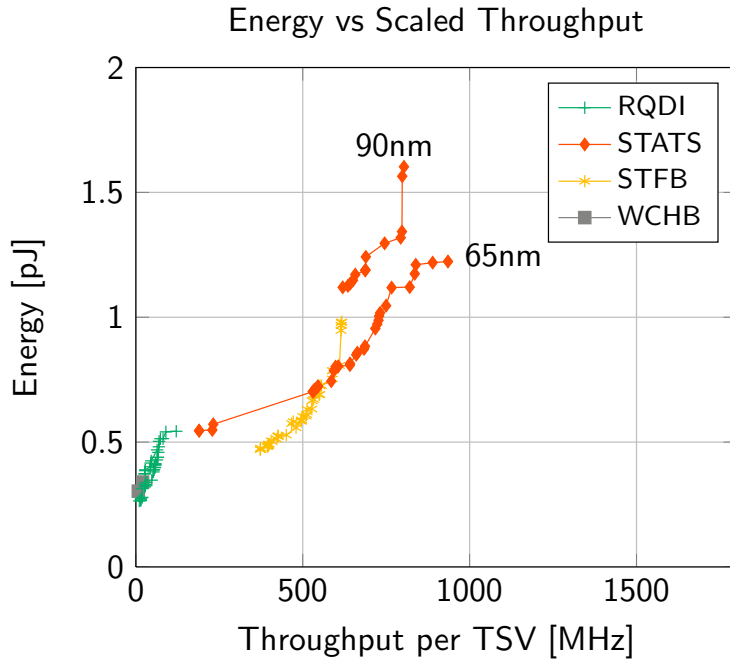
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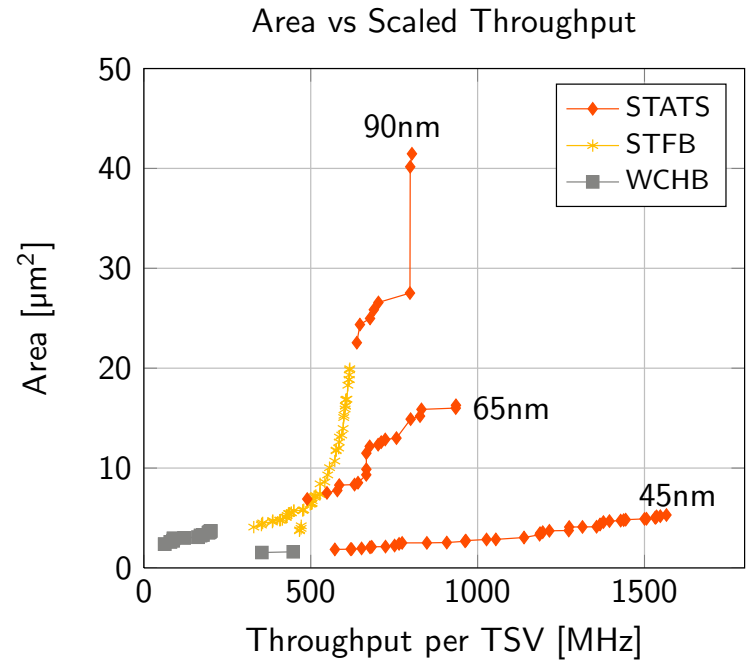
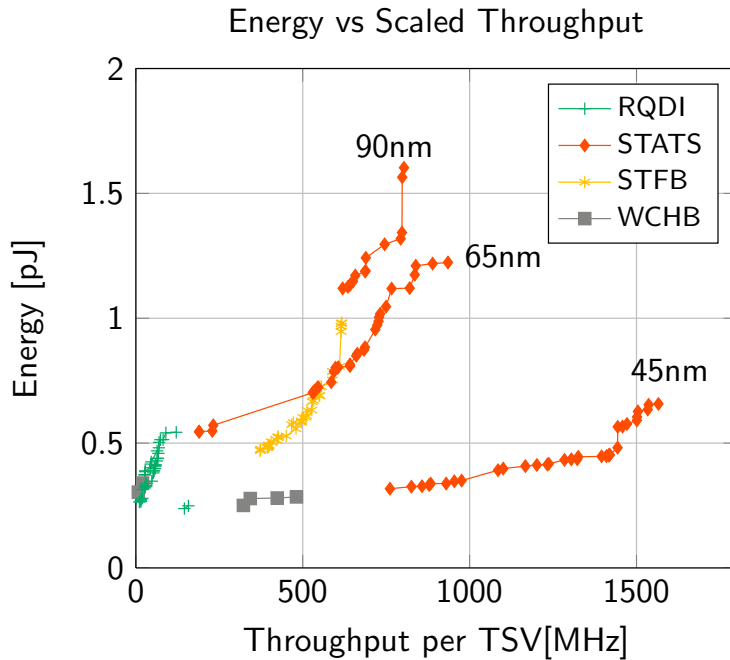
Cross-Technology TSV Results



Cross-Technology TSV Results



Cross-Technology TSV Results



TSV Takeaway Points

- ▶ TSVs are highly capacitive
 - ▶ STATS good fit
 - ▶ STFB unhappy
- ▶ STATS efficiently uses TSVs
- ▶ Interesting optimization opportunities

Conclusion

- ▶ Single-Track Timing
 - ▶ Aggressive designs offer clear benefits
 - ▶ Difficult to design
 - ▶ Not as robust
- ▶ Full-QDI
 - ▶ WCHB is most robust
 - ▶ Small penalty for robustness
- ▶ Heuristic Optimization
 - ▶ Quick design-space exploration
 - ▶ Augment/confirm designer intuition
 - ▶ Flexible, easy to implement
 - ▶ Pareto front tradeoff

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Link Failure Rates

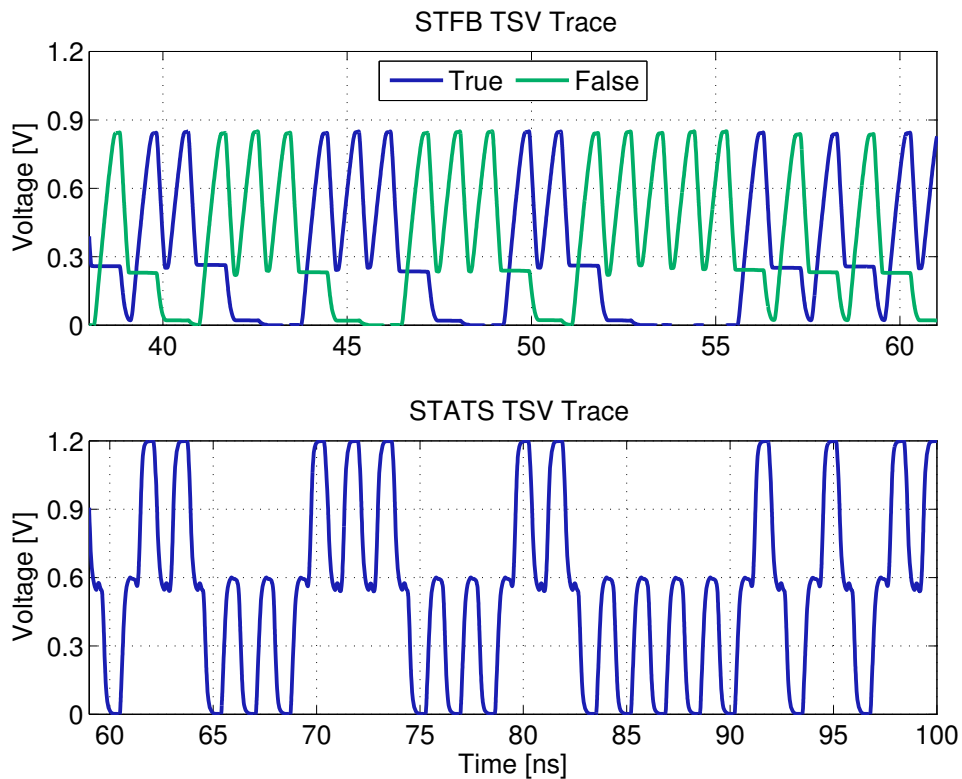
Link	% Planar Failure			% TSV Failure		
	90 nm	65 nm	45 nm	90 nm	65 nm	45 nm
ATLS	23.94	16.34	19.23	17.72	20.83	15.54
RQDI	25.60	23.93	17.80	19.72	21.52	24.68
STATS	42.40	36.26	45.45	33.26	33.96	33.31
STFB	28.18	21.99	33.63	29.19	99.33	100.00
WCHB	10.67	8.49	12.43	12.79	12.80	25.32

Note: $2856 \leq n \leq 11158$

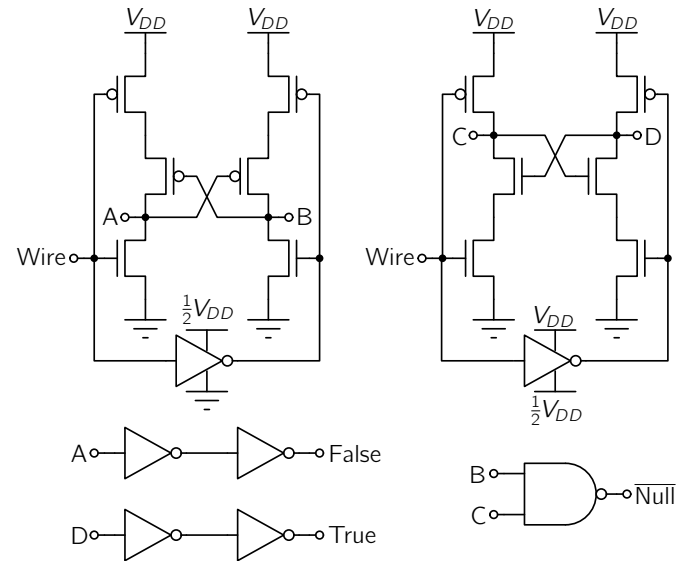
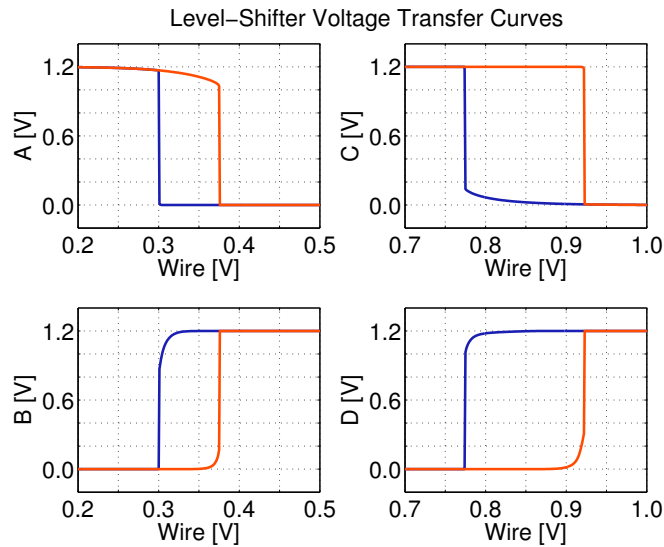
Average Sparse Wiring Energy Percentage Improvements

Link	90 nm	65 nm	45 nm
ATLS	47.36	16.93	-24.67
RQDI	33.71	7.22	13.98
STATS	27.42	-92.28	-112.87
STFB	39.04	18.11	12.26
WCHB	49.66	28.43	20.99

Single-Track Trace



Noise Margin



WCHB Level Shifters

